



Features

- Concave terminals
- Lead free version available (see How to Order "Termination" options)
- RoHS compliant*
- 8 bit multiple applications
- Smallest bussed chip array
- E 24 Series from 10 ohms to 1 megohm

CAT25 - Thick Film Chip Resistor Arrays

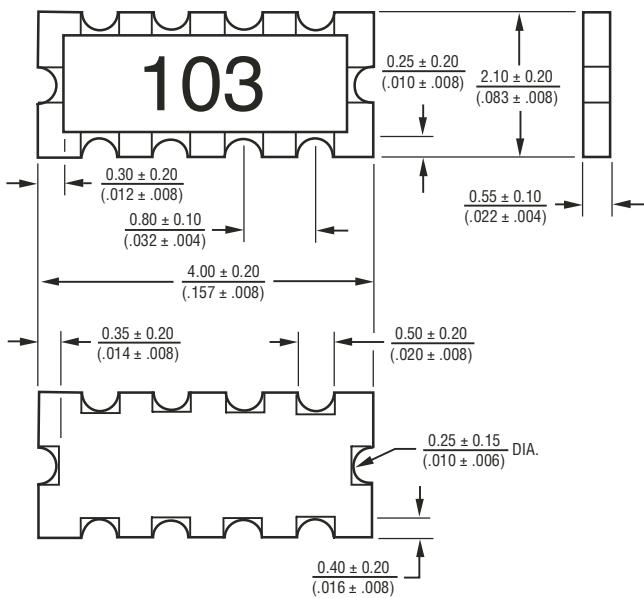
Electrical Characteristics

Parameters	CAT25	Test Method
Number of Resistors	8	
Resistance Range E24	10 ohms to 1 megohm	
Resistance Tolerance	5 %	JIS-C-5202.5.1
Power Rating/Resistor	62.5 mW	
Rating Temperature	+70 °C	
T.C.R.	+/-200 ppm/°C	JIS-C-5202.5.2
Maximum Operating Voltage	25 V	
Operating Temperature	-55 °C to +125 °C	

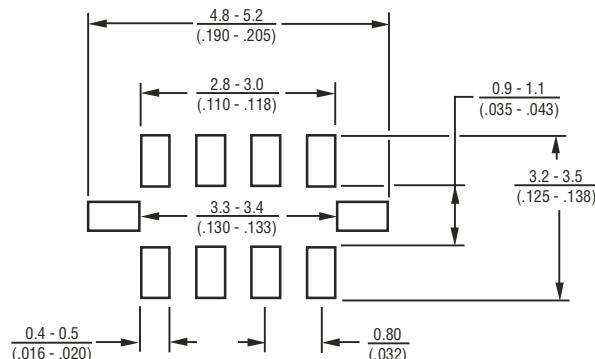
Environmental Characteristics

Specification	Characteristics	Test Method
Short Time Overload	+/- (3 % +0.1 ohm)	JIS-C-5202.5.5
Load Life	+/- (5 % +0.1 ohm)	JIS-C-5202.7.10
Humidity Load Life	+/- (3 % +0.1 ohm)	JIS-C-5202.7.9
Resistance to Soldering Heat	+/- (1 % +0.1 ohm)	JIS-C-5202.6.4
Terminal Strength	+/- (1 % +0.1 ohm)	JIS-C-5202.6.
Temperature Cycle	+/- (2 % +0.1 ohm)	JIS-C-5202.7.4
Vibration	+/- (1 % +0.1 ohm)	JIS-C-5202.6.3
Insulation Resistance	1000 megohms minimum	JIS-C-5202.5.6
Dielectric Withstanding Voltage	50 VRMS	JIS-C-5202.5.7
Lead Solderability	>95 %	JIS-C-5202.6.5

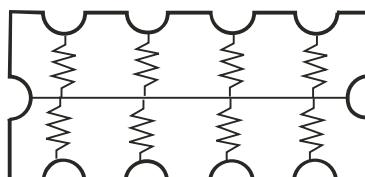
Outline Drawing



Land Pattern



Electrical Circuit

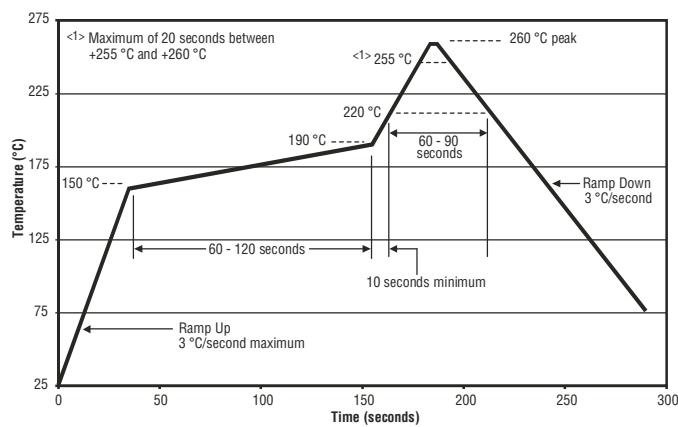


*RoHS Directive 2002/95/EC Jan 27 2003 including Annex
Specifications are subject to change without notice.
Customers should verify actual device performance in their specific applications.

CAT25 - Thick Film Chip Resistor Arrays

BOURNS®

Soldering Profile for Lead Free Chip Resistors and Arrays



Packaging

$\frac{12}{(.472)}$ embossed tape
4,000 pcs. per reel

Material

Substrate	Alumina 96
Element	Ruthenium Oxide
Coating	Glass
Terminal	AgPb, Plated Ni+SnPb

REV. 04/06

Specifications are subject to change without notice.
Customers should verify actual device performance in their specific applications.